

ABSTRACT OF THE INVENTION

An object of the present invention is to provide a wafer group that facilitates securing uniformity of products manufactured from the wafer group whose composition varies among wafers, and another object is to provide a technique of excluding uncertain factors in forming OF, forming OF with extremely high probability and extremely high accuracy, the wafer group being constituted by a plurality of wafers obtained from the same ingot, with all wafers having an orientation flat (OF), wherein the wafer group is constituted by 70 or more wafers, and in the OF orientation accuracy of the wafer group represented by an angle, the OF orientation accuracy in each wafer is within $\pm 0.010^\circ$.